## WHAT IS CLAIMED IS:

- 1. An in-vehicle electronic device comprising:
  - a conductor member;
  - an insulation member; and

an amplifying means for inputting signals from a first signal line and a second signal line and outputting amplified signals,

wherein said conductor member is provided to cover at least one of said first signal line and said second signal line via said insulation member.

- 2. The in-vehicle electronic device according to claim 1, further comprising a supporting means for supporting said first signal line, said second signal line and said amplifying means, wherein said conductor member covers, via said insulation member, any one of said first signal line and said second signal line in the opposite side of said signal line supported with said supporting means.
- 3. The in-vehicle electronic device according to claim 2, wherein said amplifying means is an operational amplifier, said supporting means is a circuit board, said first and second signal lines are metal wirings printed on said circuit board, and said insulation member and conductor member are formed as layers.
- 4. The in-vehicle electronic device according to claim 1, wherein said conductor member covers another signal line of said first and second signal lines via said insulation member.

## 5. A thermal flowmeter comprising:

a heat generating resistance body provided in the path through which the air flows; and

an electronic circuit board including an amplifying means for inputting signals from a first signal line and a second signal line and outputting the amplified signals and a conductor member for covering at least any one of said first signal line and said second signal line via an insulation member,

wherein the signal from said resistance body is inputted to said first signal line to measure flow rate of the air flowing through said path.

- 6. An electronic circuit board including a conductor layer for circuit formed on an insulated board, wherein a conductor not electrically connected to anywhere is formed, via an insulation layer, in the vicinity of a part of conductor connected to the positive input signal of an operational amplifier of the circuit portion allocated on said conductor layer for circuit and formed of a monolithic IC and a part of conductor connected to the negative input signal of said operational amplifier.
- 7. The electronic circuit board according to claim 6, wherein a metal plate not connected electrically to anywhere is formed, via the insulation layer, in the vicinity of a part of conductor connected to the positive input signal of the operational amplifier of the circuit portion allocated on said conductor layer for circuit and formed of the

monolithic IC and a part of conductor connected to the negative input signal of said operational amplifier.

- 8. The electronic circuit board according to claim 6, wherein both positive and negative input signal conductors of said operational amplifier of said circuit portion allocated on said conductor layer for circuit and formed of the monolithic IC are respectively connected to the center conductors of different shielded wires and the covering conductors of said shielded wires are not connected electrically to anywhere.
- 9. The thermal flowmeter provided with the electronic circuit board claimed in the claim 6.
- 10. The thermal flowmeter including the electronic circuit board according to claim 6, wherein said circuit board for electronic circuit forms a part of the conductor in which a metal plate not connected electrically to anywhere is connected, via the insulation layer, to the positive input signal of the operational amplifier of the circuit portion allocated on the conductor layer for circuit and formed of the monolithic IC and also forms a part of the conductor connected to the negative input signal of said operational amplifier.
- 11. The thermal flowmeter according to claim 6, wherein both positive and negative input signal conductors of the operational amplifier of the circuit portion allocated on said conductor layer for circuit and formed of the monolithic IC are respectively connected to

the center conductor of the shield wires and the covering conductors of said shield wires are terminated with each other and are not connected electrically to anywhere.